

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : F. Farassat) Group Art Unit Unknown
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 Appl. No. : Unknown)
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 Filed : Herewith)
)
 For : MECHANISM FOR)
 EXCHANGING CHIP-)
 CARRIER PLATES FOR USE)
 IN A HYBRID CHIP-)
 BONDING MACHINE)
)
 Examiner : Unknown)

6/a

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
 Washington, D.C. 20231

Dear Sir:

Prior to examination, please amend the above referenced application as follows:

IN THE ABSTRACT:

Please amend the abstract as follows:

Abstract of the Disclosure

A mechanism for exchanging chip-carrier plates in a hybrid chip-bonding machine having a plurality of chip-carrier plates, a magazine to store the plurality of chip-carrier plates, and a transport arrangement having a first and second clamping device that are disposed on a movable holder is disclosed. The transport arrangement is designed to remove a selected chip-carrier plate from the magazine and deliver it to a chip processing station. After processing, the selected chip-carrier plate is removed and deposited in the magazine. Movement of the chip-carrier plates is controlled such that the selected chip-carrier plate is positioned at a collection point to be collected from the magazine. Movement of the transport arrangement holder is controlled such that the first and second clamping devices are disposed in a vertical arrangement